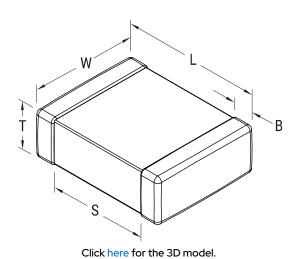


## C1808C222MBGACTU

Specifications

Insulation Resistance

Aliases (C1808C222MBGAC7800) SMD Comm COG HV, Ceramic, 2,200 pF, 20%, 630 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 1808, 2.9 mm



General Information	
Series	SMD Comm COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, Class I
Features	Ultra-Stable, Low Loss, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	62 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1808
L	4.7mm +/-0.5mm
W	2mm +/-0.2mm
Т	1.4mm +/-0.15mm
S	2.9mm MIN
В	0.6mm +/-0.35mm

	Capacitance	2,200 pF
	Measurement Condition	1 kHz 1.0Vrms
	Tolerance	20%
	Voltage DC	630 VDC
	Dielectric Withstanding Voltage	945 VDC
	Temperature Range	-55/+125°C
	Temp. Coefficient	COG
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
	Dissipation Factor	0.1% 1 kHz 1.0Vrms
	Aging Rate	0% Loss/Decade Hour

100 GOhms

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	1000

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